

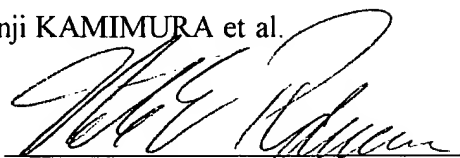
REMARKS

The above amendments have been made to make preferred changes to the claims.

Respectfully submitted,

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1. (Amended) A polishing apparatus with a polishing table having a polishing surface and a top ring for pressing a workpiece to be polished at a predetermined pressure with interposing said workpiece between said polishing table and said top ring to polish said workpiece, said polishing apparatus comprising:

at least two dressing units for dressing said polishing surface by being brought into contact with [a surface of a polishing cloth] said polishing surface.

3. (Amended) A polishing apparatus according to claim 1, wherein:

at least one dressing unit is a dressing unit comprising a dresser having a size larger than a diameter [larger than] of said workpiece to be polished; and

at least one dressing unit is a dressing unit comprising a dresser having a [diameter] size smaller than said diameter of said workpiece to be polished.

4. (Amended) A dressing method for dressing a polishing [cloth] surface provided in a polishing apparatus, wherein:

initially conditioning said polishing [cloth] surface before use in the polishing, by a dressing unit comprising a diamond dresser or an SiC dresser; and

conditioning said polishing [cloth] surface between processes of polishing said workpiece to be polished, by a dressing unit comprising a brush dresser.

5. (Amended) A dressing method for dressing a polishing [cloth] surface provided in a polishing apparatus, wherein:

initially conditioning said polishing [cloth] surface before use in the polishing, by a dressing unit comprising a diamond dresser or an SiC dresser; and

between processes of polishing said workpiece to be polished, firstly conditioning said polishing [cloth] surface by a dressing unit comprising a diamond dresser or an SiC dresser, and then conditioning said polishing [cloth] surface by a dressing unit comprising a brush dresser.

6. (Amended) A dressing method for dressing during polishing of a workpiece to be polished in a polishing apparatus, wherein:

dressing is performed while [swinging] moving a dressing unit comprising a dresser having a [diameter] size smaller than a diameter of said workpiece to be polished; and

after [a top ring is withdrawn] polishing operation is finished, dressing is performed by a dressing unit comprising a dresser having a diameter larger than said workpiece to be polished.